

Excellent Integrated System Limited

Stocking Distributor

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[TDK Corporation](#)

[MZA1210D330C](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

Chip Beads(SMD Array) For General Signal Line

Conformity to RoHS Directive

MZA Series MZA1210 Type

FEATURES

- A single MZA series chip provides noise attenuation for two lines, making it ideal for use with I/O lines of various highly miniaturized.
- Electronic equipment, such as portable products, which comprise high density circuitry.
- Low crosstalk between adjacent circuits.
- Internal electrodes feature low DC resistance, minimizing wasteful power consumption.
- Electroplated terminal electrodes accommodate reflow soldering.
- Monolithic structure ensures high reliability.
- The products contain no lead and also support lead-free soldering.
- It is a product conforming to RoHS directive.

APPLICATIONS

Removal of signal line noises of cellular phones, PCs, note PCs, TVs, DVDs, DSCs, game machines, digital photo frames, PNDs, etc.

PRODUCT IDENTIFICATION

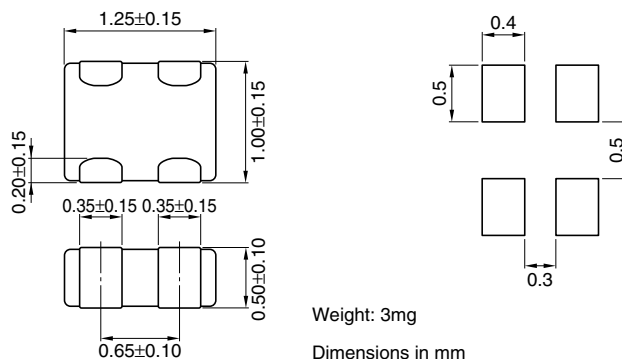
MZA 1210 D 121 C T
 (1) (2) (3) (4) (5) (6)

- (1) Series name
- (2) Dimensions L×W
- (3) Material code
- (4) Nominal impedance
121:120Ω at 100MHz
- (5) Characteristic type
- (6) Packaging style
T:Taping

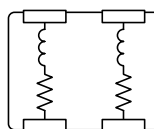
HANDLING AND PRECAUTIONS

- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and product temperature does not exceed 150°C.
- After mounting components onto the printed circuit board, do not apply stress through board bending or mishandling.
- Do not expose the inductors to stray magnetic fields.
- Avoid static electricity discharge during handling.
- When hand soldering, apply the soldering iron to the printed circuit board only. Temperature of the iron tip should not exceed 350°C. Soldering time should not exceed 3 seconds.
- This product does not apply to flow soldering construction method.

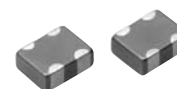
SHAPES AND DIMENSIONS/RECOMMENDED PC BOARD PATTERN



CIRCUIT DIAGRAM



• No polarity



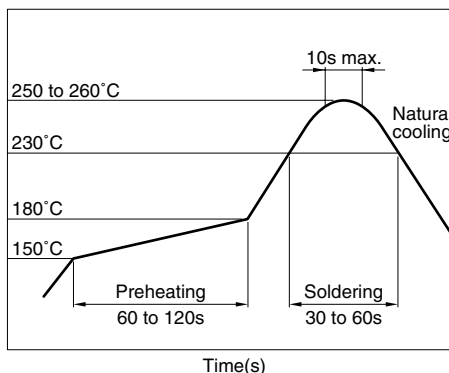
TEMPERATURE RANGES

Operating/storage -55 to +125°C

PACKAGING STYLE AND QUANTITIES

Packaging style	Quantity
Taping	5000 pieces/reel

RECOMMENDED SOLDERING CONDITION REFLOW SOLDERING



- Conformity to RoHS Directive: This means that, in conformity with EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- Please contact our Sales office when your application are considered the following:
The device's failure or malfunction may directly endanger human life (e.g. application for automobile/aircraft/medical/nuclear power devices, etc.)

ELECTRICAL CHARACTERISTICS

Part No.	Impedance(Ω) $\pm 25\%$ [100MHz]*	DC resistance (Ω)max.	Rated current (mA)max.	Rated voltage (V)max.
MZA1210D330C	33	0.3	50	5
MZA1210D680C	68	0.5	50	5
MZA1210D121C	120	0.8	50	5
MZA1210D241C	240	1.2	50	5

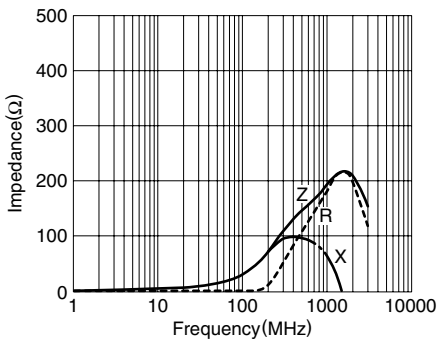
* Test equipment: E4991A or equivalent

Test tool: 16192A or equivalent

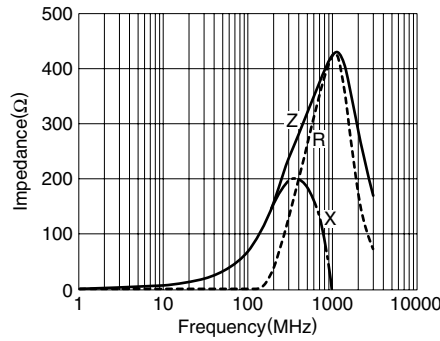
Test temperature: $25 \pm 10^\circ\text{C}$

TYPICAL ELECTRICAL CHARACTERISTICS
Z, X, R vs. FREQUENCY CHARACTERISTICS

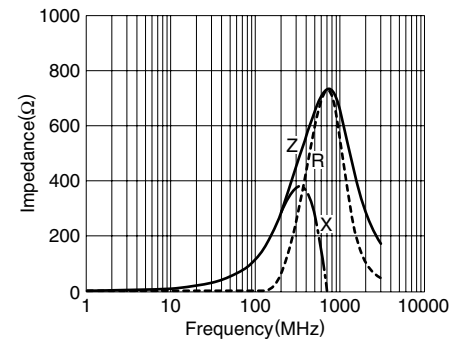
MZA1210D330C



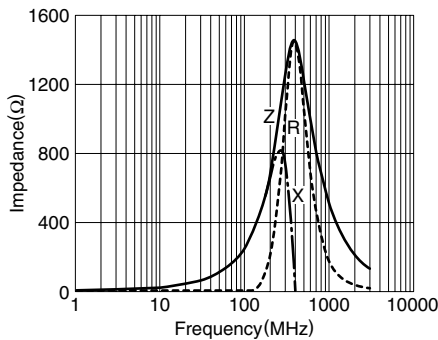
MZA1210D680C



MZA1210D121C

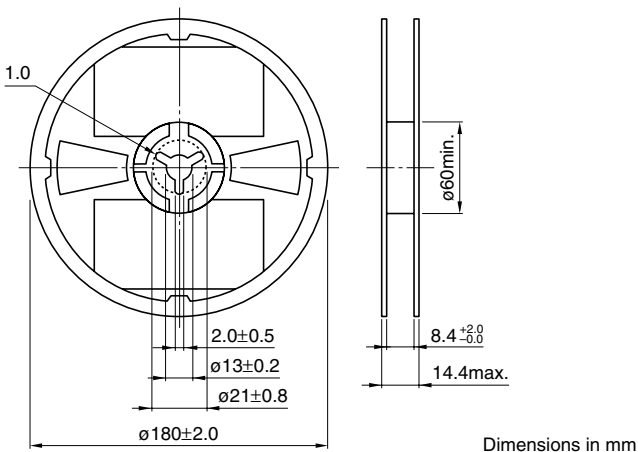


MZA1210D241C



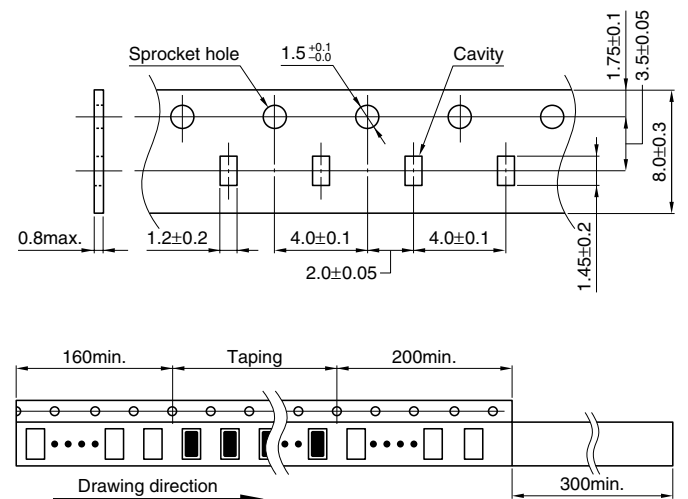
PACKAGING STYLES

REEL DIMENSIONS



Dimensions in mm

TAPE DIMENSIONS



Dimensions in mm